











uA7805, uA7808, uA7810 uA7812, uA7815, uA7824

SLVS056P-MAY 1976-REVISED JANUARY 2015

# µA78xx Fixed Positive Voltage Regulators

#### **Features**

- 3-Terminal Regulators
- Available in fixed 5-V/8-V/10-V/12-V/15-V/24-V options
- Output Current up to 1.5 A
- Internal Thermal-Overload Protection
- High Power-Dissipation Capability
- Internal Short-Circuit Current Limiting
- Output Transistor Safe-Area Compensation
- Output Capacitor Not Needed for Stability

# **Applications**

- On-card Regulation
- Portable Devices
- Computing & Servers
- **Telecommunications**

# 3 Description

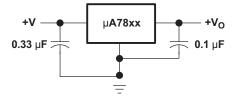
This series of fixed-voltage integrated-circuit voltage regulators is designed for a wide range of applications. These applications include on-card regulation for elimination of noise and distribution problems associated with single-point regulation. Each of these regulators can deliver up to 1.5 A of output current. The internal current-limiting and thermal-shutdown features of these regulators essentially make them immune to overload. In addition to use as fixed-voltage regulators, these devices can be used with external components to obtain adjustable output voltages and currents, and also can be used as the power-pass element in precision regulators.

#### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
	TO-220 (3)	10.16 mm x 8.82 mm
μA78xx	TO-220 (3)	10.16 mm x 8.82 mm
	TO-263 (3)	10.06 mm x 9.02 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

# **Simplified Schematic**





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# **5** Revision History

# Changes from Revision O (August 2012) to Revision P

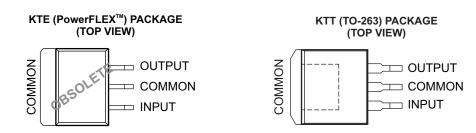
**Page** 

- Added Applications, Device Information table, Pin Functions table, ESD Ratings table, Thermal Information table,
  Typical Characteristics, Feature Description section, Device Functional Modes, Application and Implementation
  section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and
  Mechanical, Packaging, and Orderable Information section.



# 6 Pin Configuration and Functions





#### **Pin Functions**

PIN		TVDE	DESCRIPTION
NAME	NO.	TYPE	DESCRIPTION
COMMON	2	_	Ground
INPUT	1	1	Supply Input
OUTPUT	3	0	Voltage Output



# 7 Specifications

### 7.1 Absolute Maximum Ratings

over virtual junction temperature range (unless otherwise noted)

		·	MIN	MAX	UNIT
VI	lanut voltage	μA7824C		40	1/
	Input voltage	All others		35	V
$T_{J}$	Operating virtual junction temperature			150	°C
	Lead temperature	1,6 mm (1/16 in) from case for 10 s		260	°C
T <sub>stg</sub>	Storage temperature range		-65	150	°C

# 7.2 ESD Ratings

			VALUE	UNIT
		Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins (1)	3000	
V <sub>(ESD)</sub>	Electrostatic discharge	Charged device model (CDM), per JEDEC specification JESD22-C101, all pins (2)	2000	V

<sup>(1)</sup> JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

			MIN	MAX	UNIT
		μΑ7805	7	25	
		μΑ7808	10.5	25	
.,	lanut valta sa	μΑ7810	12.5	28	
√ <sub>I</sub>	Input voltage	μΑ7812	14.5	30	V
		μΑ7815	17.5	30	
		μΑ7824	27	38	
Ю	Output current			1.5	Α
Γ <sub>J</sub>	Operating virtual junction temperature		0	125	°C

#### 7.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		KTE	KCS, KCT, KC	ктт	UNIT
		3 PINS	3 PINS	3 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	23	19	25.3	
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	3	17	18	°C/W
$R_{\theta JP(top)}$	Junction-to-exposed-pad thermal resistance	2.7	3	1.94	

(1) For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report (SPRA953).

<sup>(2)</sup> JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.



### 7.5 Electrical Characteristics — uA7805

at specified virtual junction temperature,  $V_1 = 10 \text{ V}$ ,  $I_0 = 500 \text{ mA}$  (unless otherwise noted)

DADAMETED	TEST CONDITIONS	T <sub>J</sub> <sup>(1)</sup>	μΑ7805C			LINUT
PARAMETER	TEST CONDITIONS	13 (7)	MIN	TYP	MAX 5.2 5.25 100 50 100 50 8 1.3 0.5	UNIT
Output voltage	$I_0 = 5 \text{ mA to 1 A}, V_1 = 7 \text{ V to 20 V},$	25°C	4.8	5	5.2	V
Output voltage	P <sub>D</sub> ≤ 15 W	0°C to 125°C	4.75		MAX 5.2 5.25 100 50 100 50 8 1.3	V
Input valtage regulation	V <sub>I</sub> = 7 V to 25 V	25°C		3	100	m\/
Input voltage regulation	V <sub>I</sub> = 8 V to 12 V	25 C		NIN         TYP         MAX           4.8         5         5.2           .75         5.25           3         100           1         50           62         78           68         15         100           5         50           0.017         -1.1         40           2         4.2         8           1.3         1.3	50	mV
Ripple rejection <sup>(2)</sup>	V <sub>I</sub> = 8 V to 12 V, f = 120 Hz	0°C to 105°C	62	78		dB
Ripple rejection —	V <sub>I</sub> = 8 V to 12 V, f = 120 Hz (KCT)	0°C to 125°C	°C	68		uБ
Output voltage regulation	I <sub>O</sub> = 5 mA to 1.5 A	25°C		15	100	\/
	I <sub>O</sub> = 250 mA to 750 mA			5	50	mV
Output resistance	f = 1 kHz	0°C to 125°C		0.017		Ω
Temperature coefficient of output voltage	I <sub>O</sub> = 5 mA	0°C to 125°C		-1.1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz	25°C		40		μV
Dropout voltage	I <sub>O</sub> = 1 A	25°C		2		V
Bias current		25°C		4.2	8	mA
Diag assessed the same	V <sub>I</sub> = 7 V to 25 V	0°C +- 405°C			1.3	A
Bias current change	I <sub>O</sub> = 5 mA to 1 A	0°C to 125°C		68 15 100 5 50 0.017 -1.1 40 2 4.2 8 1.3	mA	
Short-circuit output current		25°C		750		mA
Peak output current		25°C		2.2		Α

<sup>(1)</sup> Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-µF capacitor across the input and a 0.1-µF capacitor across the output.

<sup>(2)</sup> This parameter is validated by design and verified during product characterization. It is not tested in production.



### 7.6 Electrical Characteristics — uA7808

at specified virtual junction temperature,  $V_1 = 14 \text{ V}$ ,  $I_0 = 500 \text{ mA}$  (unless otherwise noted)

DADAMETED	TEST CONDITIONS	T <sub>J</sub> <sup>(1)</sup>	μΑ7808C			LINUT
PARAMETER	TEST CONDITIONS	IJ ("/	MIN	TYP	MAX	UNIT
Output voltage	$I_0 = 5 \text{ mA to 1 A}, V_1 = 10.5 \text{ V to 23 V},$	25°C	7.7	8	8.3	V
Output voltage	P <sub>D</sub> ≤ 15 W	0°C to 125°C	7.6		8.4	V
	V <sub>I</sub> = 10.5 V to 25 V	25°C		6	160	mV
Input voltage regulation	V <sub>I</sub> = 11 V to 17 V	25°C		2	80	IIIV
	V <sub>I</sub> = 11.5 V to 21.5 V, f = 120 Hz		55	72		
Ripple rejection <sup>(2)</sup>	V <sub>I</sub> = 11.5 V to 21.5 V, f = 120 Hz (KCT)	0°C to 125°C		62		dB
Output voltage regulation Output resistance	I <sub>O</sub> = 5 mA to 1.5 A	25°C		12	160	m\/
	I <sub>O</sub> = 250 mA to 750 mA			4	80	mV
Output resistance	f = 1 kHz	0°C to 125°C		0.016		Ω
Temperature coefficient of output voltage	$I_O = 5 \text{ mA}$	0°C to 125°C		-0.8		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz	25°C		52		μV
Dropout voltage	I <sub>O</sub> = 1 A	25°C		2		V
Bias current		25°C		4.3	8	mA
Dies sument about	V <sub>I</sub> = 10.5 V to 25 V	000 +- 40500			1	A
Bias current change	I <sub>O</sub> = 5 mA to 1 A	0°C to 125°C			0.5	mA
Short-circuit output current		25°C		450		mA
Peak output current		25°C		2.2		Α

<sup>(1)</sup> Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-µF capacitor across the input and a 0.1-µF capacitor across the output.

<sup>(2)</sup> This parameter is validated by design and verified during product characterization. It is not tested in production.



### 7.7 Electrical Characteristics — uA7810

at specified virtual junction temperature,  $V_1 = 17 \text{ V}$ ,  $I_0 = 500 \text{ mA}$  (unless otherwise noted)

DADAMETED	TEST CONDITIONS	T <sub>J</sub> <sup>(1)</sup>	μΑ7810C			LINUT
PARAMETER	TEST CONDITIONS	17 (.,	MIN	TYP	MAX	UNIT
Output voltogo	$I_0 = 5 \text{ mA to 1 A}, V_1 = 12.5 \text{ V to 25 V},$	25°C	9.6	10	10.4	V
Output voltage	P <sub>D</sub> ≤ 15 W	0°C to 125°C	9.5	7 200 2 100	V	
Innut valtage regulation	V <sub>I</sub> = 12.5 V to 28 V	2500		7	7 200	m\/
Input voltage regulation	V <sub>I</sub> = 14 V to 20 V	25°C		2 100 55 71 12 200 4 100 0.018	mV	
Ripple rejection <sup>(2)</sup>	V <sub>I</sub> = 13 V to 23 V, f = 120 Hz	0°C to 125°C	55	71		dB
Outrod wells as as welst's a	I <sub>O</sub> = 5 mA to 1.5 A	2500		12	200	mV
Output voltage regulation	I <sub>O</sub> = 250 mA to 750 mA	25°C	4 100	IIIV		
Output resistance	f = 1 kHz	0°C to 125°C		0.018		Ω
Temperature coefficient of output voltage	I <sub>O</sub> = 5 mA	0°C to 125°C		-1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz	25°C		70		μV
Dropout voltage	I <sub>O</sub> = 1 A	25°C		2		V
Bias current		25°C		4.3	8	mA
Dies summet shares	V <sub>I</sub> = 12.5 V to 28 V	000 +- 40500			1	A
Bias current change	I <sub>O</sub> = 5 mA to 1 A	0°C to 125°C			0.5	mA
Short-circuit output current		25°C		400		mA
Peak output current		25°C		2.2		Α

<sup>(1)</sup> Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-µF capacitor across the input and a 0.1-µF capacitor across the output.

<sup>(2)</sup> This parameter is validated by design and verified during product characterization. It is not tested in production.



### 7.8 Electrical Characteristics — uA7812

at specified virtual junction temperature,  $V_1 = 19 \text{ V}$ ,  $I_0 = 500 \text{ mA}$  (unless otherwise noted)

DADAMETED	TEST CONDITIONS	T <sub>J</sub> <sup>(1)</sup>	μΑ7812C			UNIT
PARAMETER	TEST CONDITIONS	1, ('')	MIN	TYP	MAX 12.5 12.6 240 120 240 120  8 1 0.5	UNII
Output voltage	$I_0 = 5 \text{ mA to 1 A}, V_1 = 14.5 \text{ V to 27 V},$	25°C	11.5	12	12.5	V
Output voltage	P <sub>D</sub> ≤ 15 W	0°C to 125°C	11.4		12.5 12.6 240 120 240 120	V
Input valtage regulation	V <sub>I</sub> = 14.5 V to 30 V	25°C		10	240	m\/
Input voltage regulation	V <sub>I</sub> = 16 V to 22 V	25°C		3	120	mV
Ripple rejection <sup>(2)</sup>	V <sub>I</sub> = 15 V to 25 V, f = 120 Hz	0°C to 125°C	55		٩D	
Rippie rejection —	V <sub>I</sub> = 15 V to 25 V, f = 120 Hz (KCT)		55 71 61 12 4		dB	
Outrout valte as a souleties	I <sub>O</sub> = 5 mA to 1.5 A	to 1.5 A		12	240	>/
Output voltage regulation	I <sub>O</sub> = 250 mA to 750 mA		4	120	mV	
Output resistance	f = 1 kHz	0°C to 125°C		0.018		Ω
Temperature coefficient of output voltage	I <sub>O</sub> = 5 mA	0°C to 125°C		-1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz	25°C		75		μV
Dropout voltage	I <sub>O</sub> = 1 A	25°C		2		V
Bias current		25°C		4.3	8	mA
Diag assessed the same	V <sub>I</sub> = 14.5 V to 30 V	000 to 40500			1	A
Bias current change	I <sub>O</sub> = 5 mA to 1 A	0°C to 125°C			12.5 12.6 240 120 240 120	mA
Short-circuit output current		25°C		350		mA
Peak output current		25°C		2.2		Α

<sup>(1)</sup> Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-µF capacitor across the input and a 0.1-µF capacitor across the output.

<sup>(2)</sup> This parameter is validated by design and verified during product characterization. It is not tested in production.



### 7.9 Electrical Characteristics — uA7815

at specified virtual junction temperature,  $V_1 = 23 \text{ V}$ ,  $I_0 = 500 \text{ mA}$  (unless otherwise noted)

DADAMETED	TEST CONDITIONS	T <sub>J</sub> <sup>(1)</sup>	μΑ7815C			UNIT
PARAMETER	TEST CONDITIONS	1, ***	MIN	TYP	MAX	UNII
Output valtage	$I_O = 5 \text{ mA to 1 A}, V_I = 17.5 \text{ V to 30 V},$	25°C	14.4	15	15.6	V
Output voltage	P <sub>D</sub> ≤ 15 W	0°C to 125°C	14.25		15.75	V
lanut voltage regulation	V <sub>I</sub> = 17.5 V to 30 V	25°C		11	300	mV
Input voltage regulation	V <sub>I</sub> = 20 V to 26 V	25°C		3	150	mv
	V <sub>I</sub> = 18.5 V to 28.5 V, f = 120 Hz		54	70		
Ripple rejection <sup>(2)</sup>	V <sub>I</sub> = 18.5 V to 28.5 V, f = 120 Hz (KCT)	0°C to 125°C		60		dB
Output voltage regulation	I <sub>O</sub> = 5 mA to 1.5 A	25°C		12	300	\/
	I <sub>O</sub> = 250 mA to 750 mA			4	150	mV
Output resistance	f = 1 kHz	0°C to 125°C		0.019		Ω
Temperature coefficient of output voltage	I <sub>O</sub> = 5 mA	0°C to 125°C		-1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz	25°C		90		μV
Dropout voltage	I <sub>O</sub> = 1 A	25°C		2		V
Bias current		25°C		4.4	8	mA
Dies surrent about	V <sub>I</sub> = 17.5 V to 30 V	000 +- 40500			1	A
Bias current change	I <sub>O</sub> = 5 mA to 1 A	0°C to 125°C			0.5	mA
Short-circuit output current		25°C		230		mA
Peak output current		25°C		2.1		Α

<sup>(1)</sup> Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output.

<sup>(2)</sup> This parameter is validated by design and verified during product characterization. It is not tested in production.

#### 7.10 Electrical Characteristics — uA7824

at specified virtual junction temperature,  $V_1 = 33 \text{ V}$ ,  $I_0 = 500 \text{ mA}$  (unless otherwise noted)

DADAMETED	TEST CONDITIONS	T <sub>J</sub> <sup>(1)</sup>	μ			
PARAMETER	TEST CONDITIONS	1, (,,	MIN	TYP	MAX	UNIT
Output voltage	$I_0 = 5 \text{ mA to } 1 \text{ A}, V_1 = 27 \text{ V to } 38 \text{ V},$	25°C	23	24	25	V
Output voltage	P <sub>D</sub> ≤ 15 W	0°C to 125°C	22.8		25.2	V
Leavet vellage as well affect	V <sub>I</sub> = 27 V to 38 V	0500		18	480	>/
Input voltage regulation	V <sub>I</sub> = 30 V to 36 V	25°C		6	240	mV
Ripple rejection <sup>(2)</sup>	V <sub>I</sub> = 28 V to 38 V, f = 120 Hz	0°C to 125°C	50	66		dB
Outrot wells as as what's	I <sub>O</sub> = 5 mA to 1.5 A	0500		12	480	>/
Output voltage regulation	I <sub>O</sub> = 250 mA to 750 mA	25°C		4	240	mV
Output resistance	f = 1 kHz	0°C to 125°C		0.028		Ω
Temperature coefficient of output voltage	I <sub>O</sub> = 5 mA	0°C to 125°C		-1.5		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz	25°C		170		μV
Dropout voltage	I <sub>O</sub> = 1 A	25°C		2		V
Bias current		25°C		4.6	8	mA
D'accomment de com	V <sub>I</sub> = 27 V to 38 V	000 1- 40500		0.5		1
Bias current change	I <sub>O</sub> = 5 mA to 1 A	0°C to 125°C				mA
Short-circuit output current		25°C		150		mA
Peak output current		25°C		2.1		Α

<sup>(1)</sup> Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-µF capacitor across the input and a 0.1-µF capacitor across the output.

# 7.11 Typical Characteristics

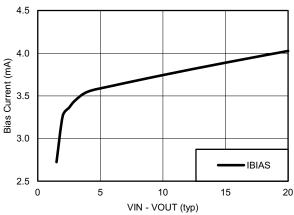


Figure 1. µA7805 Bias Current vs Voltage Differential at 25°C

<sup>(2)</sup> This parameter is validated by design and verified during product characterization. It is not tested in production.

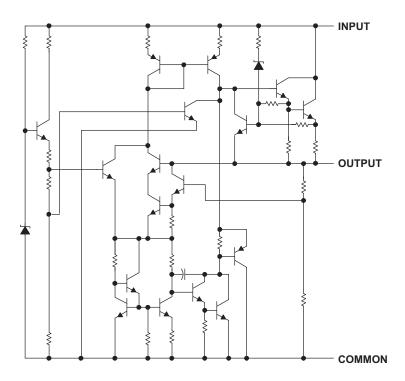


# 8 Detailed Description

#### 8.1 Overview

This series of fixed-voltage integrated-circuit voltage regulators is designed for a wide range of applications. These applications include on-card regulation for elimination of noise and distribution problems associated with single-point regulation. Each of these regulators can deliver up to 1.5 A of output current. The internal current-limiting and thermal-shutdown features of these regulators essentially make them immune to overload. In addition to use as fixed-voltage regulators, these devices can be used with external components to obtain adjustable output voltages and currents, and also can be used as the power-pass element in precision regulators.

#### 8.2 Functional Schematic



# 8.3 Feature Description

#### 8.3.1 Thermal Overload

When the die temperature increases to unwanted levels, the device will reduce the output current to lower its temperature. Under heavy loads, the device may alternate between on and off output states to regulate temperature.

# 8.3.2 Short-Circuit Current Limiting

In the event of a short circuit, the device will limit its own current to safe levels by lowering the bias voltage of internal pass transistors. If the device becomes overheated, the thermal overload protection will take over.

#### 8.4 Device Functional Modes

#### 8.4.1 Fixed-Output Mode

These devices are available in fixed-output voltages. See the orderable part list for the desired output.

# 9 Application and Implementation

#### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

#### 9.1 Application Information

The following section shows application details of the µA78xx as a linear regulator.

## 9.2 Typical Application

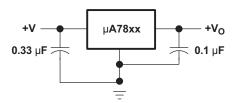


Figure 2. Fixed-Output Regulator

#### 9.2.1 Design Requirements

- · Input supply capacitor recommended for filtering noise on the input
- Output supply decoupling capacitor for stabilizing the output

#### 9.2.2 Detailed Design Procedure

#### 9.2.2.1 Operation With a Load Common to a Voltage of Opposite Polarity

In many cases, a regulator powers a load that is not connected to ground but, instead, is connected to a voltage source of opposite polarity (e.g., operational amplifiers, level-shifting circuits, etc.). In these cases, a clamp diode should be connected to the regulator output as shown in Figure 3. This protects the regulator from output polarity reversals during startup and short-circuit operation.

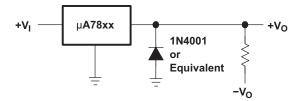


Figure 3. Output Polarity-Reversal-Protection Circuit

#### 9.2.2.2 Reverse-Bias Protection

Occasionally, the input voltage to the regulator can collapse faster than the output voltage. This can occur, for example, when the input supply is crowbarred during an output overvoltage condition. If the output voltage is greater than approximately 7 V, the emitter-base junction of the series-pass element (internal or external) could break down and be damaged. To prevent this, a diode shunt can be used as shown in Figure 4.



# **Typical Application (continued)**

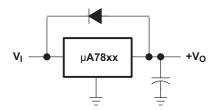


Figure 4. Reverse-Bias-Protection Circuit

#### 9.2.3 Application Curves

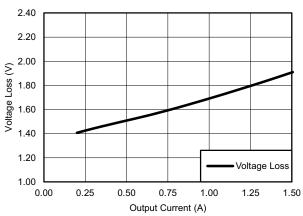


Figure 5. µA7805 Voltage Loss vs Output Current at 25°C

## 9.2.4 General Configurations

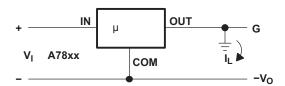
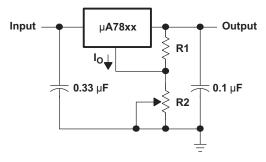


Figure 6. Positive Regulator in Negative Configuration (V<sub>I</sub> Must Float)



A: The following formula is used when  $V_{XX}$  is the nominal output voltage (output to common) of the fixed regulators

$$V_{o} = V_{xx} + \left(\frac{V_{xx}}{R1} + I_{o}\right)R2$$

Figure 7. Adjustable-Output Regulator

# **Typical Application (continued)**

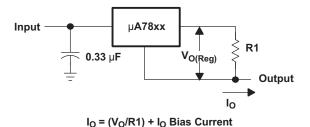


Figure 8. Current Regulator

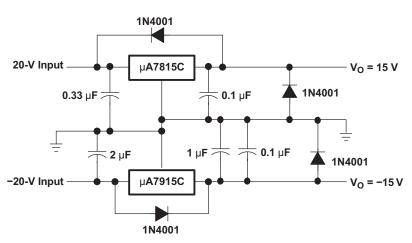


Figure 9. Regulated Dual Supply

# 10 Power Supply Recommendations

See Recommended Operating Conditions for the recommended power supply voltages for each variation of the  $\mu$ A78xx device. Different orderable part numbers will be able to tolerate different levels of voltage. It is also recommended to have a decoupling capacitor on the output of the  $\mu$ A78xx device's power supply to limit noise on the device input.



# 11 Layout

### 11.1 Layout Guidelines

Keep trace widths large enough to eliminate problematic IxR voltage drops at the input and output terminals. Input decoupling capacitors should be placed as close to the μA78XX as possible.

#### 11.2 Layout Example

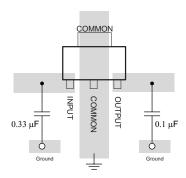


Figure 10. Layout Diagram

### 12 Device and Documentation Support

#### 12.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

**TECHNICAL TOOLS & SUPPORT & PARTS** PRODUCT FOLDER **SAMPLE & BUY DOCUMENTS SOFTWARE** COMMUNITY µA7805 Click here Click here Click here Click here Click here uA7808 Click here Click here Click here Click here Click here uA7810 Click here Click here Click here Click here Click here uA7812 Click here Click here Click here Click here Click here uA7815 Click here Click here Click here Click here Click here uA7924 Click here Click here Click here Click here Click here

**Table 1. Related Links** 

#### 12.2 Trademarks

#### 12.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

# 12.4 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

# 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.





12-Jan-2015

### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
UA7805CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI	0 to 125	UA7805C	
UA7805CKCE3	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI	0 to 125	UA7805C	
UA7805CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7805C	Samples
UA7805CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7805C	Samples
UA7805CKCT	ACTIVE	TO-220	KCT	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7805C	Samples
UA7805CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI	0 to 125	UA7805C	
UA7805CKTTR	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	0 to 125	UA7805C	Samples
UA7805CKTTRG3	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	0 to 125	UA7805C	Samples
UA7805QKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI	-40 to 125		
UA7805QKTE	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI	-40 to 125		
UA7808CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI	0 to 125	UA7808C	
UA7808CKCE3	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI	0 to 125	UA7808C	
UA7808CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7808C	Samples
UA7808CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7808C	Samples
UA7808CKCT	ACTIVE	TO-220	KCT	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7808C	Samples
UA7808CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI	0 to 125	UA7808C	
UA7808CKTTR	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	0 to 125	UA7808C	Samples
UA7808CKTTRG3	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	0 to 125	UA7808C	Samples
UA7808QKTE	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI	-40 to 125		
UA7810-W	ACTIVE	WAFERSALE	YS	0	3952	TBD	Call TI	Call TI			Samples
UA7810CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI	0 to 125	UA7810C	
UA7810CKCE3	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI	0 to 125	UA7810C	





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sample
UA7810CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7810C	Sample
UA7810CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7810C	Sample
UA7810CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI	0 to 125	UA7810C	
UA7810CKTTR	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	0 to 125	UA7810C	Sample
UA7810CKTTRG3	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	0 to 125	UA7810C	Sample
UA7810QKTE	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI	-40 to 125		
UA7812CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI	0 to 125	UA7812C	
UA7812CKCE3	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI		UA7812C	
UA7812CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7812C	Sample
UA7812CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7812C	Sample
UA7812CKCT	ACTIVE	TO-220	KCT	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7812C	Sample
UA7812CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI	0 to 125	UA7812C	
UA7812CKTTR	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	0 to 125	UA7812C	Sample
UA7812CKTTRG3	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	0 to 125	UA7812C	Sample
UA7812QKTE	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI	-40 to 125		
UA7815CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI	0 to 125	UA7815C	
UA7815CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7815C	Sample
UA7815CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7815C	Sample
UA7815CKCT	ACTIVE	TO-220	KCT	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7815C	Sample
UA7815CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI	0 to 125	UA7815C	
UA7815CKTTR	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	0 to 125	UA7815C	Sample
UA7815QKTE	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI			



# PACKAGE OPTION ADDENDUM

12-Jan-2015

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
UA7824CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI	0 to 125	UA7824C	
UA7824CKCE3	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI	0 to 125	UA7824C	
UA7824CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7824C	Samples
UA7824CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7824C	Samples
UA7824CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI	0 to 125	UA7824C	
UA7824CKTTR	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	0 to 125	UA7824C	Samples
UA7885CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI			
UA7885CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI			
UA7885QKTE	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI			

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



# PACKAGE OPTION ADDENDUM

12-Jan-2015

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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# TAPE AND REEL INFORMATION



# TAPE DIMENSIONS KO P1 BO W Cavity A0

	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

*All dimensions are nomina	ıl				1							1
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UA7805CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.8	16.1	4.9	16.0	24.0	Q2
UA7805CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.8	16.3	5.11	16.0	24.0	Q2
UA7808CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.8	16.3	5.11	16.0	24.0	Q2
UA7810CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.8	16.3	5.11	16.0	24.0	Q2
UA7812CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.8	16.1	4.9	16.0	24.0	Q2
UA7812CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.8	16.3	5.11	16.0	24.0	Q2
UA7815CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.8	16.3	5.11	16.0	24.0	Q2
UA7824CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.8	16.3	5.11	16.0	24.0	Q2

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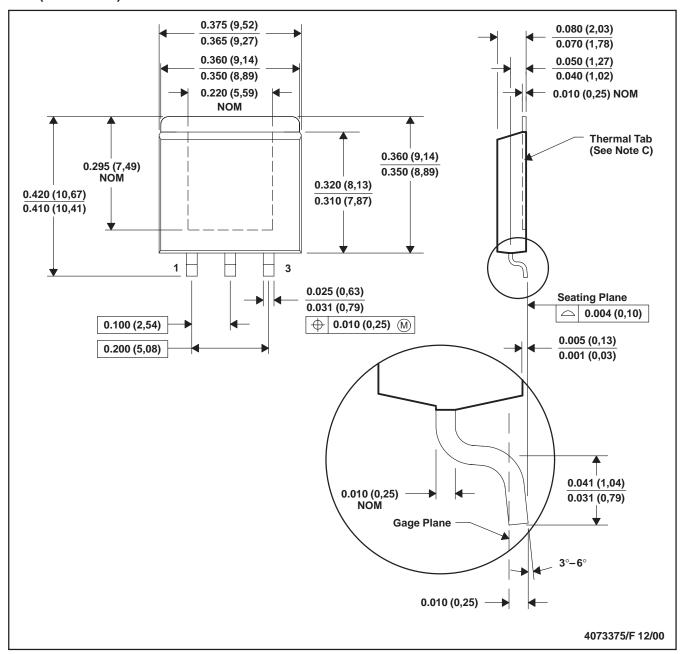


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UA7805CKTTR	DDPAK/TO-263	KTT	3	500	350.0	334.0	47.0
UA7805CKTTR	DDPAK/TO-263	KTT	3	500	340.0	340.0	38.0
UA7808CKTTR	DDPAK/TO-263	KTT	3	500	340.0	340.0	38.0
UA7810CKTTR	DDPAK/TO-263	KTT	3	500	340.0	340.0	38.0
UA7812CKTTR	DDPAK/TO-263	KTT	3	500	350.0	334.0	47.0
UA7812CKTTR	DDPAK/TO-263	KTT	3	500	340.0	340.0	38.0
UA7815CKTTR	DDPAK/TO-263	KTT	3	500	340.0	340.0	38.0
UA7824CKTTR	DDPAK/TO-263	KTT	3	500	340.0	340.0	38.0

### KTE (R-PSFM-G3)

#### **PowerFLEX™ PLASTIC FLANGE-MOUNT**



- NOTES: A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. The center lead is in electrical contact with the thermal tab.
  - D. Dimensions do not include mold protrusions, not to exceed 0.006 (0,15).
  - E. Falls within JEDEC MO-169

PowerFLEX is a trademark of Texas Instruments.



# KTT (R-PSFM-G3)

# PLASTIC FLANGE-MOUNT PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- 3. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash or protrusion not to exceed 0.005 (0,13) per side.
- ⚠ Falls within JEDEC T0—263 variation AA, except minimum lead thickness and minimum exposed pad length.



# KTT (R-PSFM-G3)

# PLASTIC FLANGE-MOUNT PACKAGE



NOTES: A.

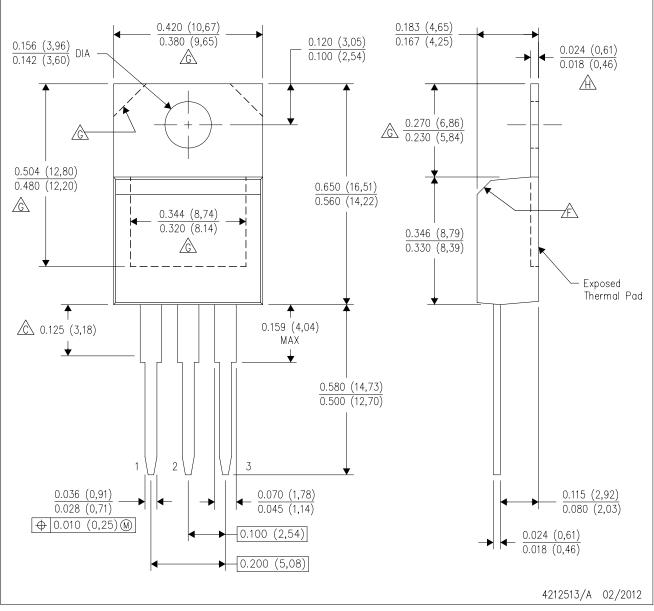
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-SM-782 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release.

  Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.
- F. This package is designed to be soldered to a thermal pad on the board. Refer to the Product Datasheet for specific thermal information, via requirements, and recommended thermal pad size. For thermal pad sizes larger than shown a solder mask defined pad is recommended in order to maintain the solderable pad geometry while increasing copper area.



# KCT (R-PSFM-T3)

## PLASTIC FLANGE-MOUNT PACKAGE



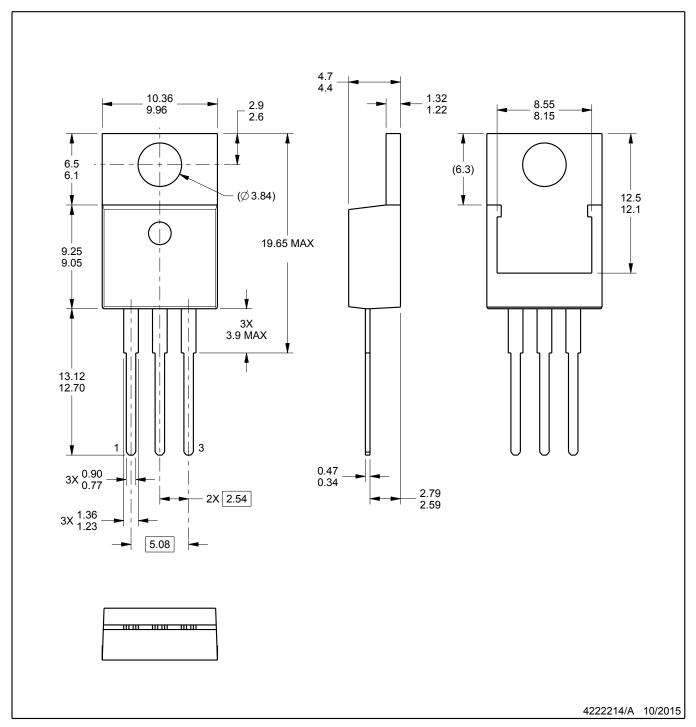
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Lead dimensions are not controlled within this area.
- D. All lead dimensions apply before solder dip.
- E. The center lead is in electrical contact with the mounting tab.
- The chamfer is optional.
- Thermal pad contour optional within these dimensions.
- Falls within JEDEC TO-220 variation AB, except minimum tab thickness.





TO-220

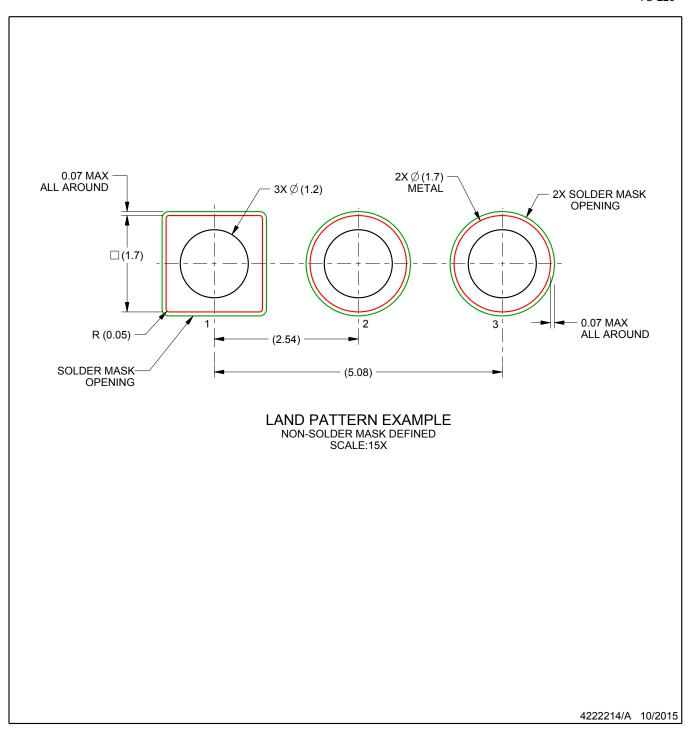


#### NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
   Reference JEDEC registration TO-220.

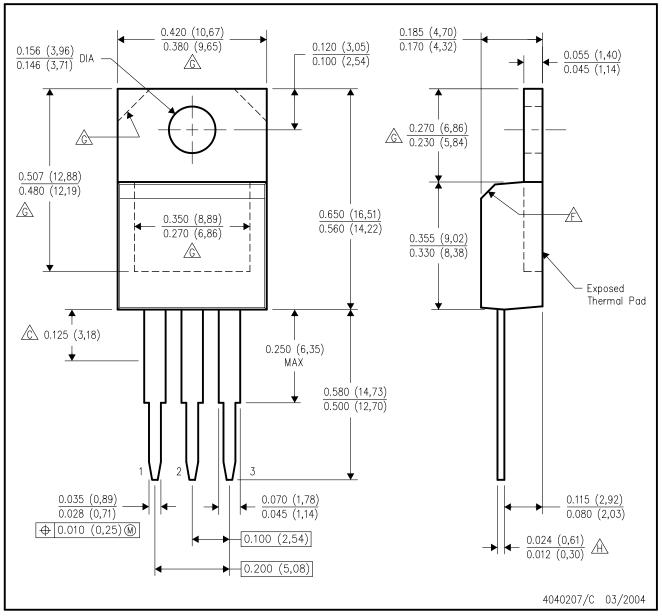


TO-220



# KC (R-PSFM-T3)

# PLASTIC FLANGE-MOUNT PACKAGE



NOTES: A. All linear

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Lead dimensions are not controlled within this area.
- D. All lead dimensions apply before solder dip.
- E. The center lead is in electrical contact with the mounting tab.
- The chamfer is optional.
- Thermal pad contour optional within these dimensions.
- Falls within JEDEC TO-220 variation AB, except minimum lead thickness.



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#### Products Applications

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive **Amplifiers** amplifier.ti.com Communications and Telecom www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps DSP dsp.ti.com **Energy and Lighting** www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical Logic Security www.ti.com/security logic.ti.com

Power Mgmt power.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers microcontroller.ti.com Video and Imaging www.ti.com/video

RFID www.ti-rfid.com

OMAP Applications Processors www.ti.com/omap TI E2E Community e2e.ti.com

Wireless Connectivity www.ti.com/wirelessconnectivity